

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT3757650

<b>SUBMISSION TYPE:</b>	CORRECTIVE ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	Corrective Assignment to correct the ADD THE FIFTH INVENTOR previously recorded on Reel 037519 Frame 0750. Assignor(s) hereby confirms the ASSIGNMENT OF ASSIGNORS INTEREST.
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YUKI MORI	11/05/2015
TOSHIYUKI MINE	11/05/2015
HIROSHI MIKI	11/05/2015
MIEKO MATSUMURA	11/05/2015
HIROTAKA HAMAMURA	11/05/2015
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HITACHI, LTD.
<b>Street Address:</b>	6-6, MARUNOUCHI 1-CHOME
<b>City:</b>	CHIYODA-KU, TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	100-8280
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14904685
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)610-8686
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	7039039000
<b>Email:</b>	tpurifoy@milesstockbridge.com, ipdocketing@milesstockbridge.com
<b>Correspondent Name:</b>	ERIC G. KING
<b>Address Line 1:</b>	MILES & STOCKBRIDGE P.C.
<b>Address Line 2:</b>	1751 PINNACLE DRIVE, SUITE 1500
<b>Address Line 4:</b>	TYSONS CORNER, VIRGINIA 22102-3833
<b>ATTORNEY DOCKET NUMBER:</b>	XA-13032/T3381-22104US01
<b>NAME OF SUBMITTER:</b>	TYNISHA PURIFOY
<b>SIGNATURE:</b>	/Tynisha Purifoy/
<b>DATE SIGNED:</b>	02/26/2016

**Total Attachments: 8**

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<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT3700634

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YUKI MORI	11/05/2015
TOSHIYUKI MINE	11/05/2015
HIROSHI MIKI	11/05/2015
MIEKO MATSUMURA	11/05/2015
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HITACHI, LTD.
<b>Street Address:</b>	6-6, MARUNOUCHI 1-CHOME
<b>City:</b>	CHIYODA-KU, TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	100-8280
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14904685
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)610-8686
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	7039039000
<b>Email:</b>	tpurifoy@milesstockbridge.com, ipdocketing@milesstockbridge.com
<b>Correspondent Name:</b>	ERIC G. KING
<b>Address Line 1:</b>	MILES & STOCKBRIDGE P.C.
<b>Address Line 2:</b>	1751 PINNACLE DRIVE, SUITE 1500
<b>Address Line 4:</b>	TYSONS CORNER, VIRGINIA 22102-3833
<b>ATTORNEY DOCKET NUMBER:</b>	XA-13032/T3381-22104US01
<b>NAME OF SUBMITTER:</b>	TYNISHA PURIFOY
<b>SIGNATURE:</b>	/Tynisha Purifoy/
<b>DATE SIGNED:</b>	01/19/2016
<b>Total Attachments: 5</b>	
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source=Assignment#page2.tif	

**ASSIGNMENT**  
( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD.,  
a corporation organized under the laws of Japan,  
located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan,  
receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD.,  
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI, LTD.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1)	<i>Yuki Mori</i> (Yuki MORI)	<i>November 5, 2015</i>
2)	(Toshiyuki MINE)	
3)	(Hiroshi MIKI)	
4)	(Mieko MATSUMURA)	
5)	(Hiroataka HAMAMURA)	
6)		
7)		
8)		

ASSIGNMENT  
(讓渡証)

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Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (發明者フルネームサイン)	Date Signed (署名日)
1) _____ (Yuki MORI)	_____
2) <u>Toshiyuki Mine</u> (Toshiyuki MINE)	<u>November 5, 2015</u>
3) _____ (Hiroshi MIKI)	_____
4) _____ (Mieko MATSUMURA)	_____
5) _____ (Hiroataka HAMAMURA)	_____
6) _____	_____
7) _____	_____
8) _____	_____

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Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネーム、サイン)	Date Signed (署名日)
1) _____ (Yuki MORI)	_____
2) _____ (Toshiyuki MINE)	_____
3) <u>Hiroshi Miki</u> _____ (Hiroshi MIKI)	<u>November 5, 2015</u>
4) _____ (Mieko MATSUMURA)	_____
5) _____ (Hiroiaka HAMAMURA)	_____
6) _____	_____
7) _____	_____
8) _____	_____

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Signed on the date(s) indicated aside our signatures:

INVENTOR(S)  
(發明者フルネームサイン)

Date Signed  
(署名日)

1) _____ (Yuki MORI)	_____
2) _____ (Toshiyuki MINE)	_____
3) _____ (Hiroshi MIKI)	_____
4) <u>Mieko Matsumura</u> (Mieko MATSUMURA)	<u>November 5, 2015</u>
5) _____ (Hiroataka HAMAMURA)	_____
6) _____	_____
7) _____	_____
8) _____	_____

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to be held and enjoyed by said HITACHI, LTD.,

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2) _____ (Toshiyuki MINE)	_____
3) _____ (Hiroshi MIKI)	_____
4) _____ (Mieko MATSUMURA)	_____
5) <u>Hiroataka Hamamura</u> (Hiroataka HAMAMURA)	<u>November 5, 2015</u>
6) _____	_____
7) _____	_____
8) _____	_____